

AN622-TX2-EN50

Features

- Fanless and ruggedized design.
- Extended temperature range -20°C to 55°C.
- Specifically designed for high performance and low-power envelope AI computing
- Additional driver to support Embedded peripheral modules for multiple I/O expansion capability

Specifications

System Carrier Board

- ACE-N622

Module

- NVIDIA Jetson TX2 Module

Construction

- SGCC

Chassis Color

- Black

Front Panel External I/O

- 1x RJ45(10/100/1000M)
- 2x RJ45(POE Optional)
- 1x HDMI
- 2x USB 3.0 Type A
- 1x USB 2.0 OTG
- 1x DC Jack
- 2x CAN (DB9)
- Power Button

Rear Panel External I/O

- 2x SMA connector
- 1x SD card

Expansion Slot

- 1x Full size Mini PCI-E socket(mPCIe + mSATA)

Power Supply

- DC 9~19V

Dimension

- 156(W) x 126.7(D) x 89.5(H)mm

Operating Temperature

- -20°C ~ +55°C

Operating Humidity

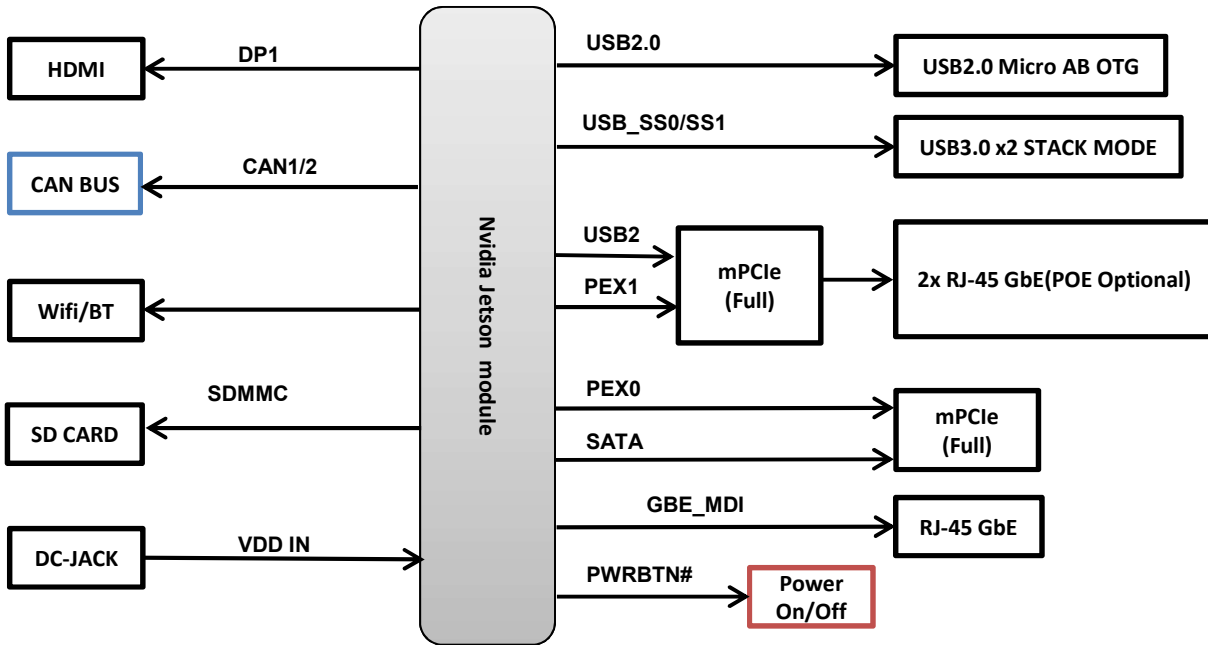
- 10% ~ 95%

Storage Temperature

- -40°C ~ +85°C



Block Diagram



Mechanical

